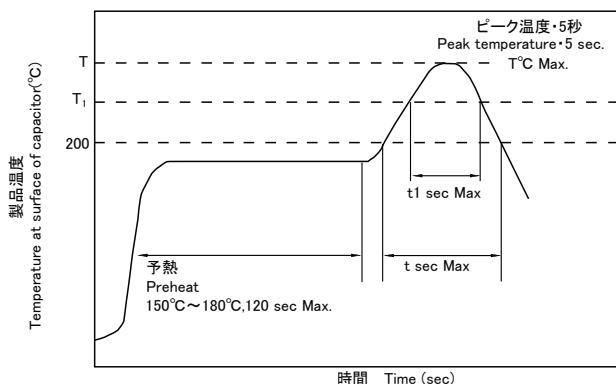
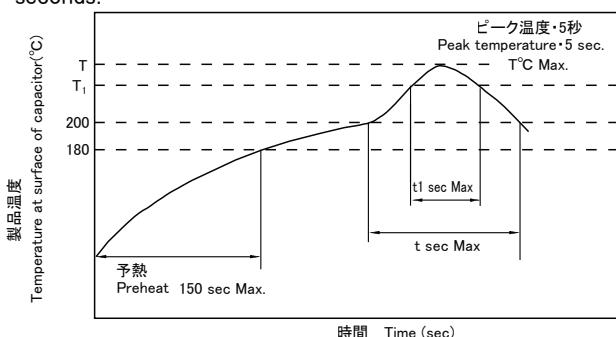


◆鉛フリータイプリフロー許容条件／LEAD FREE TYPE REFLOW SOLDERING CONDITION

●ケースサイズ $\phi 4 \sim \phi 10$ mm品 Size $\phi 4 \sim \phi 10$ 1) コンデンサ表面温度が $T^{\circ}\text{C}$ 以下である事。Temperature at surface of capacitor shall not exceed $T^{\circ}\text{C}$.2) コンデンサ表面温度は 200°C 以上の時間が t 秒, $T_1^{\circ}\text{C}$ 以上の時間が t_1 秒を越えない事。Period that temperature at surface of capacitor becomes more than 200°C and $T_1^{\circ}\text{C}$ shall not exceed t and t_1 seconds, respectively.3) 予熱は $150^{\circ}\text{C} \sim 180^{\circ}\text{C}$ で120秒以内である事。Preheat shall be made at $150^{\circ}\text{C} \sim 180^{\circ}\text{C}$ and for maximum 120 seconds.

Series	Size	Rated Voltage	T($^{\circ}\text{C}$) ①	T1($^{\circ}\text{C}$)	t(sec) ②	t1(sec) ③	Reflow cycle
SEV	$\phi 4 \sim \phi 6.3$	$\leq 50\text{Vdc}$	250	230	70	30	2
SKV	$\phi 8$	$\leq 100\text{Vdc}$	245	230	70	30	2
SGV	$\phi 10$	$\leq 160\text{Vdc}$	240	230	60	30	2
TZV							
TKV							
TPV							
TLV							
TRV							
TXV							
THV							
TGV							
TAV							
TSV							
TNV							
SJV	$\phi 4 \sim \phi 6.3$	$\leq 50\text{Vdc}$	240	220	60	40	1
SLV	$\phi 8, 10$	$\leq 50\text{Vdc}$	260	217	-	60	2
JGV	$\phi 4 \sim \phi 6.3$	$\leq 50\text{Vdc}$	250	217	-	60	2

①ピーク温度 Peak temperature

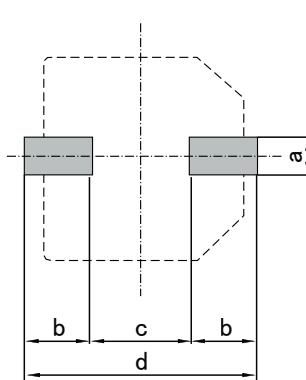
② 200°C を超える時間<MAX> Time more than 200°C ③ $T_1^{\circ}\text{C}$ を超える時間<MAX> Time more than $T_1^{\circ}\text{C}$ ※許容条件を越える場合は御相談ください。
Please contact us if the condition is over the maximum.●ケースサイズ $\phi 12.5 \sim \phi 18$ mm品 Size $\phi 12.5 \sim \phi 18$ 1) コンデンサ表面温度が $T^{\circ}\text{C}$ 以下である事。Temperature at surface of capacitor shall not exceed $T^{\circ}\text{C}$.2) コンデンサ表面温度は 200°C 以上の時間が t 秒, $T_1^{\circ}\text{C}$ 以上の時間が t_1 秒を越えない事。Period that temperature at surface of capacitor becomes more than 200°C and $T_1^{\circ}\text{C}$ shall not exceed t and t_1 seconds, respectively.3) 予熱は $100^{\circ}\text{C} \sim 180^{\circ}\text{C}$ で150秒以内である事。Preheat shall be made at $100^{\circ}\text{C} \sim 180^{\circ}\text{C}$ and for maximum 150 seconds.

Series	Size	Rated Voltage	T($^{\circ}\text{C}$) ①	T1($^{\circ}\text{C}$)	t(sec) ②	t1(sec) ③	Reflow cycle
SEV	$\phi 12.5 \sim \phi 18$	$\leq 50\text{Vdc}$	240	230	60	30	2
SKV		63Vdc	240	230	50	20	2
SGV		100Vdc					
TLV							
TRV							
TGV							
TSV		$\geq 160\text{Vdc}$	230	220	50	20	2

①ピーク温度 Peak temperature

② 200°C を超える時間<MAX> Time more than 200°C ③ $T_1^{\circ}\text{C}$ を超える時間<MAX> Time more than $T_1^{\circ}\text{C}$ ※許容条件を越える場合は御相談ください。
Please contact us if the condition is over the maximum.

◆推奨ランドパターン/RECOMMENDED LAND PATTERN



Size	a	b	c	d
$\phi 4$	1.6	2.6	1.0	6.2
$\phi 5$	1.6	3.0	1.4	7.4
$\phi 6.3$	1.6	3.5	2.1	9.1
$\phi 8 \times 6.5$	1.6	4.5	2.1	11.1
$\phi 8 \times 10.5$	2.2	4.1	3.0	11.2
$\phi 10 \times 10.5$	2.2	4.3	4.5	13.1
$\phi 12.5$	2.5	6.0	5.0	17
$\phi 16$	3	6.5	8.0	21
$\phi 18$	3	7.5	8.0	23